

<b>PCN Number:</b>	20220804000.1	<b>PCN Date:</b>	August 04, 2022
<b>Title:</b>	Qualification of TI Malaysia as an additional assembly site for select Devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Nov 4, 2022	<b>Sample requests accepted until:</b>	Sept 4, 2022*
<b>*Sample requests received after Sept 4, 2022 will not be supported.</b>			
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>			
<b>Description of Change:</b>			
Texas Instruments Incorporated is announcing the qualification of TI Malaysia as an alternate Assembly site for devices listed below in the product affected section. Construction differences are as follows:			
	<b>UTL2</b>	<b>TI Malaysia</b>	
Mount Compound	SID#PZ0013	4147858	
Bond wire composition/diameter	Au, 1.3mil	Cu, 1.3 mil or 1.0 mil	
Mold Compound	SID#CZ0239	4211880	
<b>Reason for Change:</b>			
Supply continuity			
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>			
None			
<b>Impact on Environmental Ratings</b>			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change
<b>Changes to product identification resulting from this PCN:</b>			
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>
UTL2	NS2	THA	Bangpakong
<b>MLA</b>	<b>MLA</b>	<b>MYS</b>	<b>Kuala Lumpur</b>
Sample product shipping label (not actual product label)			



MADE IN: Malaysia  
2DC: 20:



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

MSL 2 /260C/1 YEAR SEAL DT  
MSL 1 /235C/UNLIM 03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750

**Product Affected:**

DRV134PA	OPA177GP	SN65HVD1780P	SN65HVD1785P
INA134PA	OPA445AP	SN65HVD1781P	SN65HVD1786P
OPA134PA	OPA551PA	SN65HVD1782P	UCC3804N
OPA177FP			

TI Information  
Selective Disclosure

**Qualification Report**  
Approve Date 01-August-2022

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	QBS Reference: ADC0832CCN/NOBP	QBS Reference: LM231AN/NOBP	QBS Reference: LM2594HVN- ADJ/NOBP	QBS Reference: LMC6482IN/NOBP
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	3/231/0	3/231/0	3/231/0
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	3/228/0	3/228/0	3/228/0	3/228/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	3/228/0	3/228/0	3/228/0	3/228/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/15/0	3/15/0	3/15/0	3/15/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2204-078

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
WW Change Management Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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